

COM-QM87

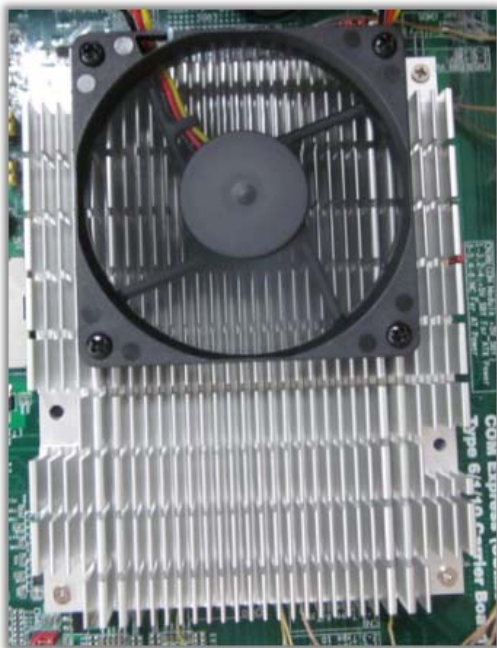
Thermal Image Analysis Report

| | | | | |
|---------------------|---|-------|-------|-------------|
| Summary | <input type="checkbox"/> Pass <input type="checkbox"/> Fail <input checked="" type="checkbox"/> Pass with Deviation <p style="text-align: center;"><u>Comment: Temperature points at 1 components were estimated to be in marginal temperature points in comparion with component datasheets.</u></p> | | | |
| Test Result Summary | | | | |
| | Critical | Major | Minor | Enhancement |
| Defect Found | 0 | 0 | 0 | 1 |
| Defect Unsolved | 0 | 0 | 0 | 1 |

| | | | |
|------------|----------|-----------|---------------|
| Issue date | Approval | Issued by | Test Engineer |
| 2013/06/19 | TOM | Rex Chang | ET Chen |

Sample Configuration & Quantity Under Test

- Model name : COM-QM87 A0.2
- CPU Board : COM-QM87 A0.2
- CPU : Intel Core i5-4400E (2.70 GHz)
- Memory : Transcend DDR3L 1600 8GB x 2
- HDD : WD WD5000AAKX 3.5" 500G
- BIOS : COM-QM87 R0.2 (CM87AM02)
- Test Software : Windows 7/ Run PassMark Burn In Test 7.0
- Power : AT Power
- Cooler:



Thermal Image Analysis

1. Test Date: 2013-06-18

2. Test Product: COM-QM87

3. Test Site: QE Dept.

4. Temperature Measurement:

4.1. 40 Channel Thermal Recorder:

4.1.1 OMRON Inc,

4.2.2 Model: ZR-RX40

Date of Calibration: 2012/12/11

Serial Number: H004528074.2. IR Scanner: Infrared Camera

4.2.1 NEC

4.2.2 Model: G100D

Date of Calibration: 2013-01-08

Serial Number: 1051444

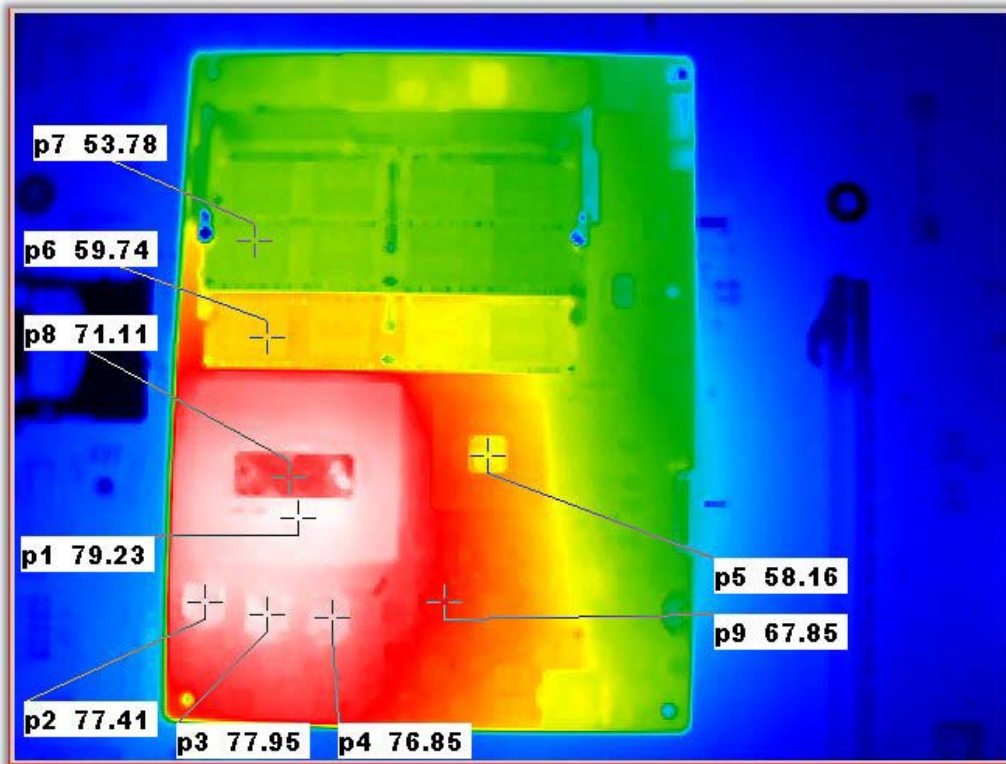
5. Test Condition:

Component Side-1 (Test by ZR-RX40):25.0°C With CPU Fan

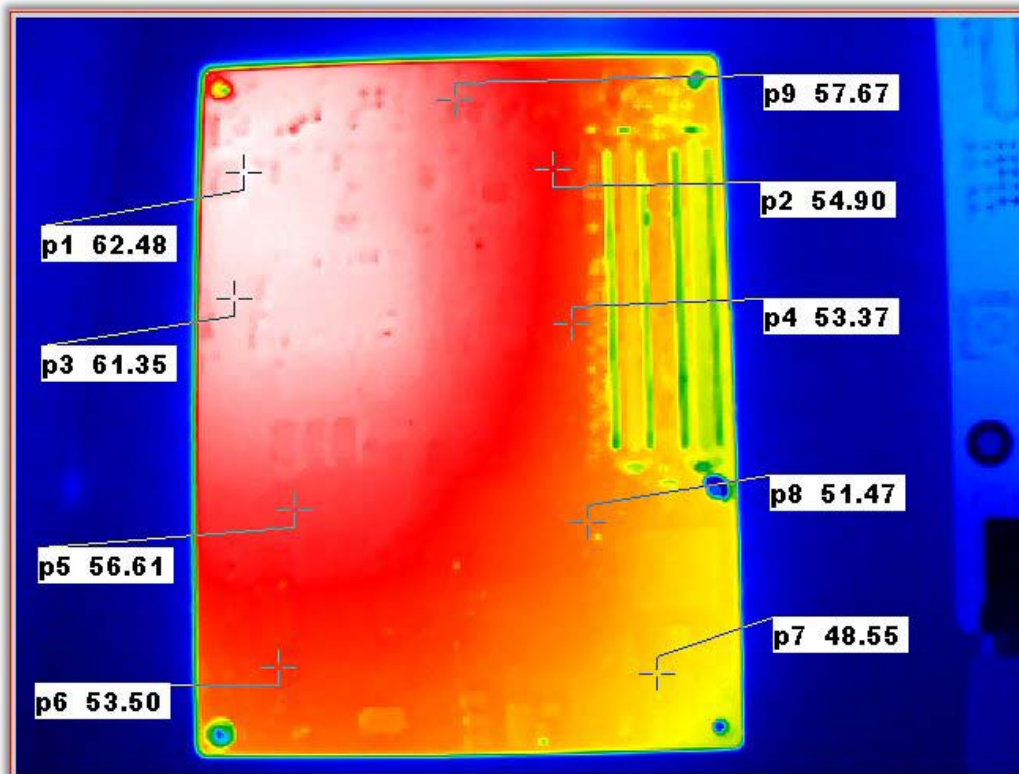
6. Take Picture Time:

After power on 2 hours

**Temperature Profile Test:
Component Side:**

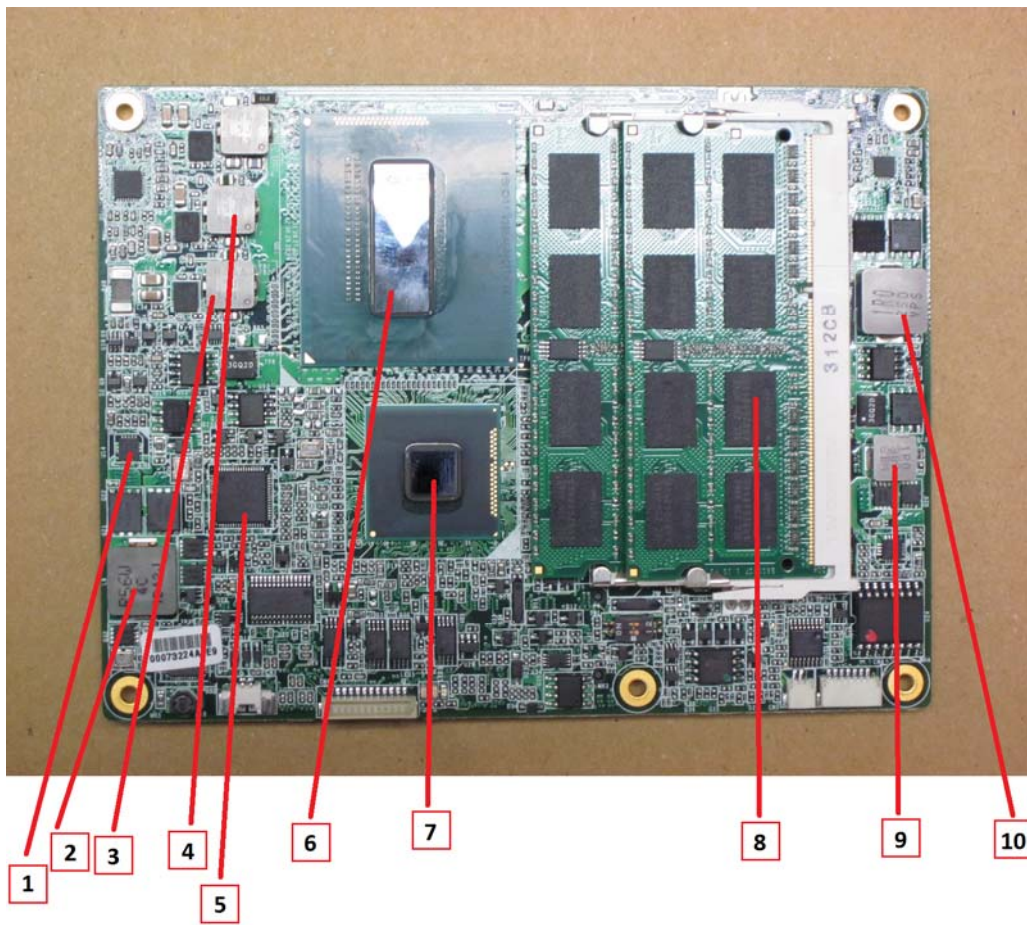


Back Side:



Terminal Recorder:

Measuring Thermal Couple Position :



Using YOKOGAWA / DARWIN DA100-100-13-1D test

| Point | Position | Describe | Tc (*1) (°C) | Tm (*2) Measured Under | | Note |
|-------|----------|---|-----------------|---------------------------|------|-------|
| | | | | 25°C | 60°C | |
| 1 | U14 | Single Synchronous.Step-Down Controller.TI.TPS51217DSCR | 100 | 49.1 | 84.1 | |
| 2 | L9 | Simple Sequencers.AD.ADM1085AKSZ | 130 | 39.4 | 74.4 | |
| 3 | L3 | Panasonic.ETQP4LR24AFM | 130 | 41.1 | 76.1 | |
| 4 | L2 | Panasonic.ETQP4LR24AFM | 130 | 43.0 | 78.0 | |
| 5 | U16 | DisplayPort to LVDS Converter.Chrontel.CH7511B-BF | 85 | 51.4 | 86.4 | Note4 |
| 6 | U5 | INTEL CPU.Haswell Mobile.BGA1364P | 100 | 45.0 | 80.0 | |
| 7 | U15 | Chipset PCH.SMD.INTEL.BD82QM87 | 108 | 44.2 | 79.2 | |
| 8 | Memory | Transcend DDR3L 1600 8GB | 85 | 41.8 | 76.8 | |
| 9 | L8 | GOTREND.GSTC063P-1R0MN | 125 | 43.2 | 78.2 | |
| 10 | L4 | GOTREND.GSTC104P-1R0MN | 125 | 41.4 | 76.4 | |

Note(*):

1. "Tc" indicates the component's case maximum temperature value specified in its datasheet.
2. "Tm" indicates the measured Tc value under working environmental temperature within product specification.

3. Judgment Criteria:

- Fail : $T_m > T_c + 5^\circ\text{C}$; The measured value is over specification plus margin.
- Margin : $T_c + 5^\circ\text{C} > T_m > T_c - 10^\circ\text{C}$; The measured value is within specification with margin.
For FANLESS system application, it is strongly recommended to add thermal dissipation design for better reliability.
- Pass : $T_m < T_c - 10^\circ\text{C}$; The measured value is with safety margin.

4. Defect No. **C121209QED01**